ABBOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pa	PC. Bannock	burn, Illinois, A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration entities the declaration entities and the declaration entities and the declaration entities and the declaration entities are an entite	on of the su acompasses	bstances v all lower	vithin the manufactu level materials for w	rer listed i which the r	tem. Note: nanufacture	if the item is an as r has engineering	sembly with lowe responsibility.	
				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials a				ials and M	s and Mfg Information				
Supplier Information														
Company name* Com			Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi										2025-06	2025-06-04			
ontact Name Title - Contact			ct	F			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Env			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repre			presentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date Version Manufacturin		Ianufacturing Site		Weight*	UOM	Unit Type		
	NRVTS G	RVTS10100MFST1 Low Vf 10A, 10		0V Trench Schotky		2025-06-04		М	MY1		113.069	mg	Each	
Manufacturing Proccess Informa	tion													
Terminal Plating / Grid Array M	aterial	ial Terminal Base Alloy		J-STD-020 MSI	STD-020 MSL Rating		Peak Process Body Temperat		ure Max Time at Peak Terr		ture Num	ber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	secor	nds 3				
omments														
vel 1 - maximum time at peak temperat	ure during so	dering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.8	mg	Supplier	Zinc (Zn)	7440-66-6		0.0058	mg
			Supplier	Iron (Fe)	7439-89-6		0.1128	mg
			Supplier	Copper (Cu)	7440-50-8		4.68	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Die	0.713	mg	Supplier	Silicon (Si)	7440-21-3		0.713	mg
Die Attach Solder	11.9	mg	Supplier	Silver (Ag)	7440-22-4		0.2975	mg
			А	Lead (Pb)	7439-92-1	7a	11.0075	mg
			Supplier	Tin (Sn)	7440-31-5		0.595	mg
Lead Frame	47.44	mg	Supplier	Iron (Fe)	7439-89-6		0.0474	mg
			Supplier	Copper (Cu)	7440-50-8		47.3783	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0142	mg
ead Frame plating	0.13	mg	Supplier	Silver (Ag)	7440-22-4		0.13	mg
Mold Compound-Black	47.136	mg		Epoxy resin	proprietary data		3.5352	mg
			Supplier	Phenolic Resin	Proprietary Data		1.1784	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.5352	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2357	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.6515	mg
Plating	0.95	mg	Supplier	Tin (Sn)	7440-31-5		0.95	mg